1.1GHz Low-Voltage Dual Modulus Prescaler

MC12022LVA
MC12022LVB

MECL PLL COMPONENTS

÷64/65, ÷128/129
DUAL MODULUS
PRESCALER

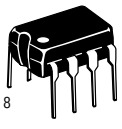
The MC12022LVA can be used with CMOS synthesizers requiring positive edges to trigger internal counters such as Motorola's MC145XXX series in a PLL to provide tuning signals up to 1.1GHz in programmable frequency steps.

The MC12022LVB can be used with CMOS synthesizers requiring negative edges to trigger internal counters.

A Divide Ratio Control (SW) permits selection of a 64/65 or 128/129 divide ratio as desired.

The Modulus Control (MC) selects the proper divide number after SW has been biased to select the desired divide ratio.

- 1.1 GHz Toggle Frequency
- Supply Voltage of 2.7 to 5.0V
- Low–Power 4.0mA Typical at V_{CC} = 2.7V
- Operating Temperature Range of –40 to +85°C
- Short Setup Time (t_{set}) 16ns Maximum @ 1.1GHz
- Modulus Control Input Level Is Compatible With Standard CMOS and TTL



P SUFFIX
PLASTIC PACKAGE
CASE 626–05

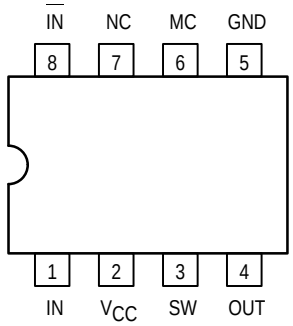
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751–05

FUNCTIONAL TABLE

SW	MC	Divide Ratio
H	H	64
H	L	65
L	H	128
L	L	129

Note: SW: H = V_{CC}, L = Open
MC: H = 2.0 V to V_{CC}, L = GND to 0.8 V

Pinout: 8–Lead Plastic (Top View)



DESIGN GUIDE

Criteria	Value	Unit
Internal Gate Count*	67	ea
Internal Gate Propagation Delay	200	ps
Internal Gate Power Dissipation	0.75	mW
Speed Power Product	0.15	pJ

* Equivalent to a two–input NAND gate

MAXIMUM RATINGS

Symbol	Characteristic	Range	Unit
V_{CC}	Power Supply Voltage, Pin 2	–0.5 to + 7.0	Vdc
T_A	Operating Temperature Range	–40 to + 85	°C
T_{stg}	Storage Temperature Range	–65 to + 150	°C
MC	Modulus Control Input, Pin 6	–0.5 to + 6.5	Vdc

MOTOROLA

ELECTRICAL CHARACTERISTICS (V_{CC} = 2.7 to 5.0V; T_A = –40°C to +85°C)

Symbol	Characteristic	Min	Typ	Max	Unit
f_t	Toggle Frequency (Sine Wave Input)	0.1	1.4	1.1	GHz
I_{CCL}	Supply Current Output Unloaded (Pin 2) at 2.7Vdc		4.7	6.5	mA
I_{CCH}	Supply Current Output Unloaded (Pin 2) at 5.0Vdc		5.8	8.0	mA
V_{IH1}	Modulus Control Input High (MC)	2.0		V_{CC} + 0.5V	V
V_{IL1}	Modulus Control Input Low (MC)			0.8	V
V_{IH2}	Divide Ratio Control Input High (SW)	V_{CC} – 0.5V	V_{CC}	V_{CC} + 0.5V	Vdc
V_{IL2}	Divide Ratio Control Input Low (SW)	Open	Open	Open	—
V_{out}	Output Voltage Swing C_L = 12pF; R_L = 1.1kΩ at 2.7Vdc	0.8	1.0		V_{p-p}
V_{out}	Output Voltage Swing C_L = 12pF; R_L = 2.2kΩ at 5.0Vdc	1.0	1.6		V_{p-p}
t_{set}	Modulus Setup Time MC to Out		11	16	ns
$V_{in(min)}$	Input Voltage Sensitivity 250–1100 MHz 100–250 MHz	100 400		1500 1500	mVpp
I_O	Output Current C_L = 12pF; R_L = 1.1kΩ at 2.7Vdc C_L = 12pF; R_L = 2.2kΩ at 5.0Vdc		1.2 1.2	4.0 4.0	mA

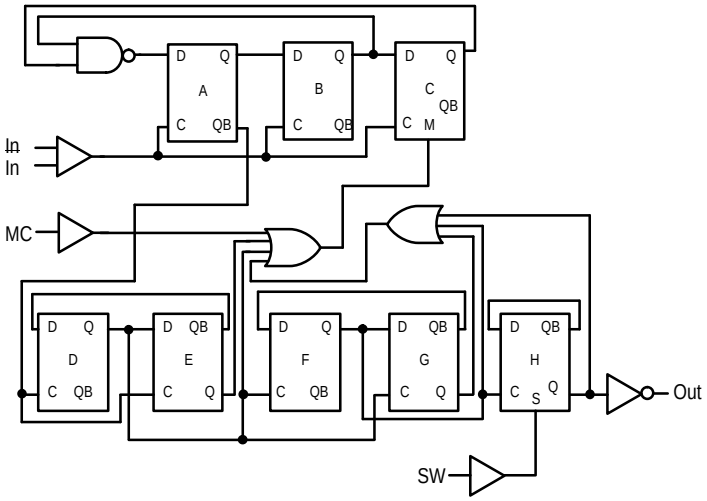
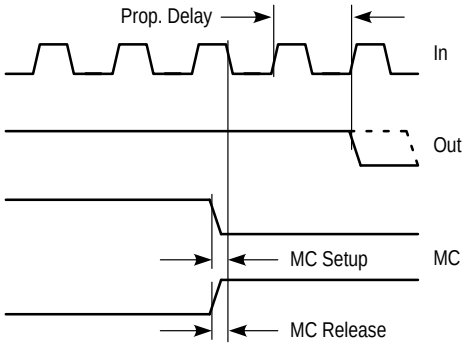
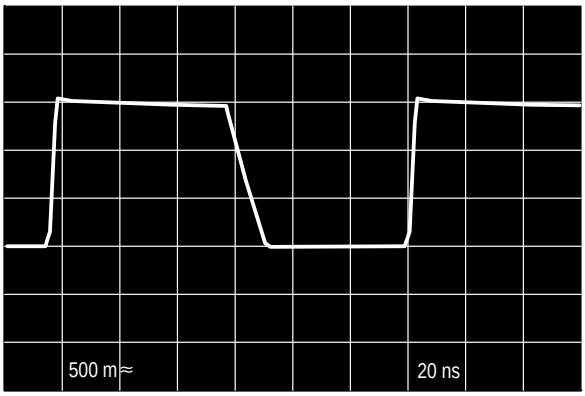


Figure 1. Logic Diagram (MC12022LVA)

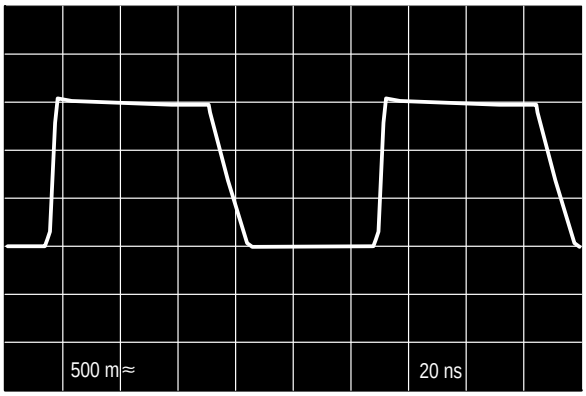


Modulus setup time MC to out is the MC setup or MC release plus the prop delay.

Figure 2. Modulus Setup Time



(÷64, 500MHz Input Frequency, V_{CC} = 5.0V, T_A = 25°C, Output Loaded)



(÷128, 1.1GHz Input Frequency, V_{CC} = 5.0V, T_A = 25°C, Output Loaded)

Figure 3. Typical Output Waveforms

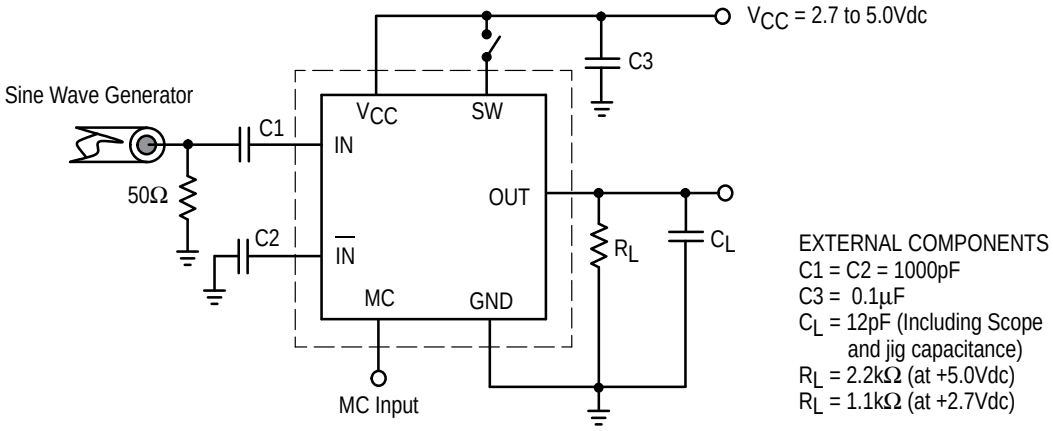


Figure 4. AC Test Circuit

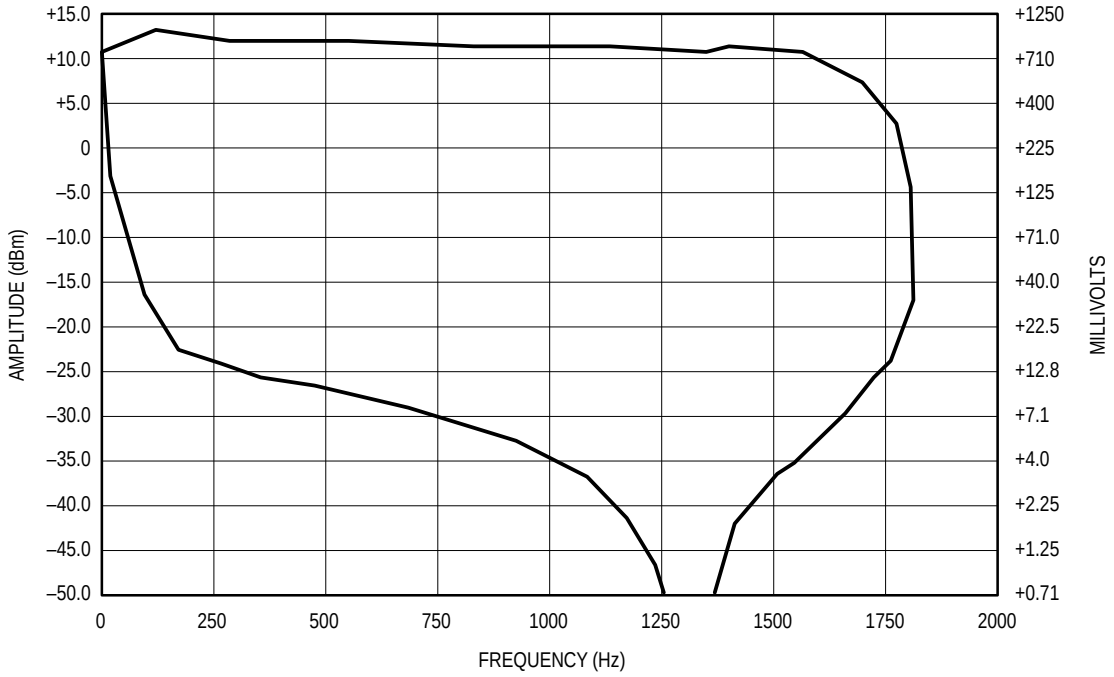


Figure 5. Input Signal Amplitude versus Input Frequency
Divide Ratio = 128; V_{CC} = 5.0V; T_A = 25°C

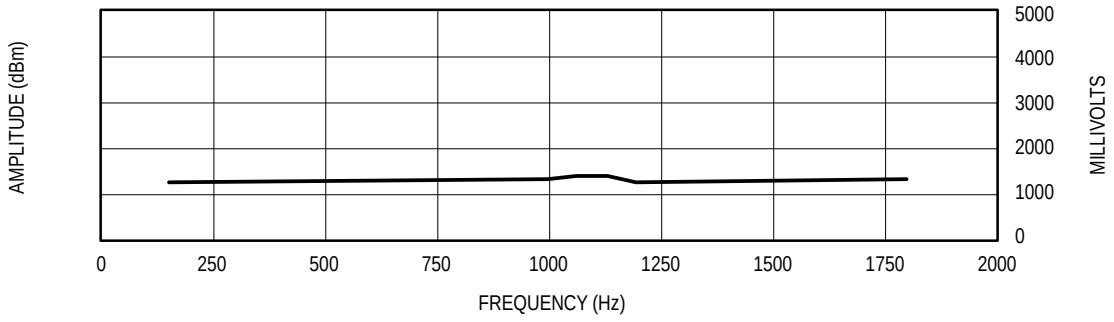


Figure 6. Output Amplitude versus Input Frequency

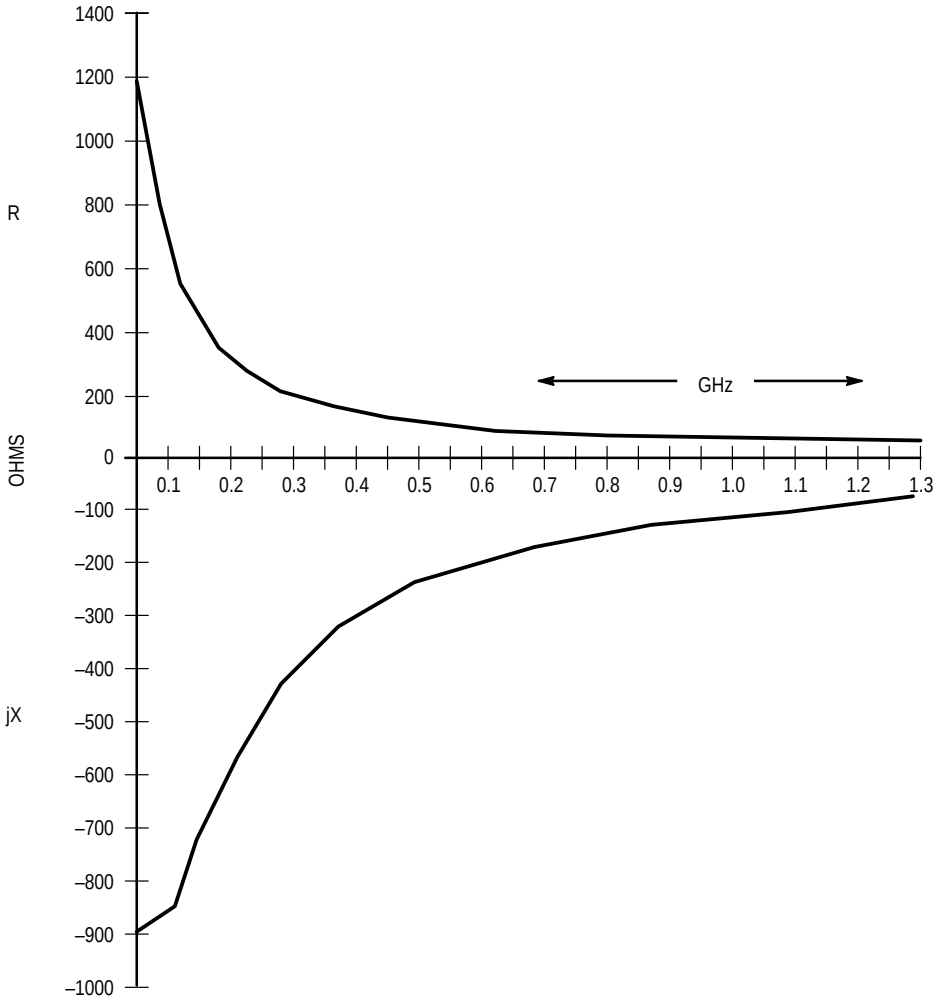
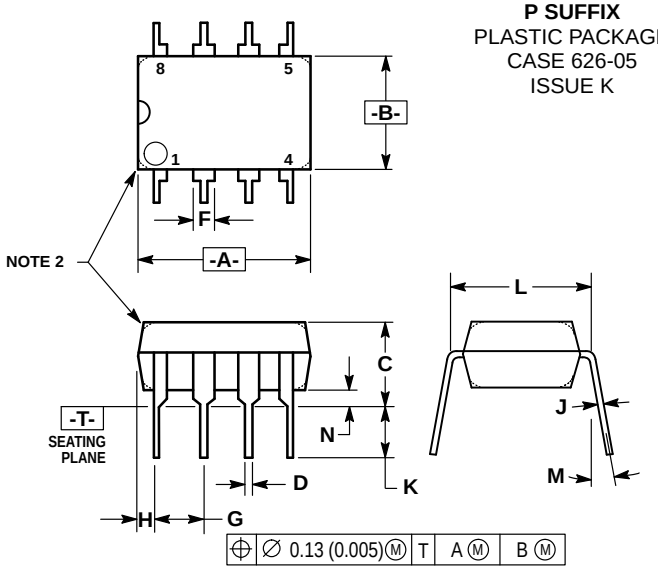


Figure 7. Typical Input Impedance versus Input Frequency

OUTLINE DIMENSIONS

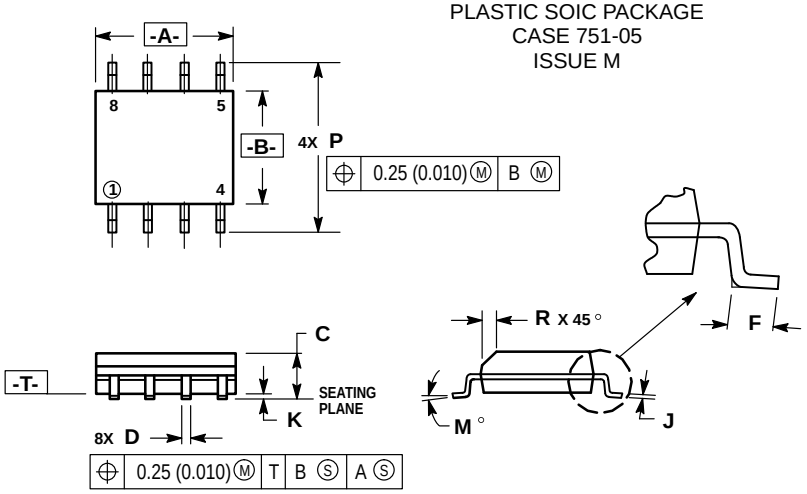
P SUFFIX
PLASTIC PACKAGE
CASE 626-05
ISSUE K



NOTES:
1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	—	10°	—	10°
N	0.76	1.01	0.030	0.040

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751-05
ISSUE M



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.196
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.18	0.25	0.007	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

Literature Distribution Centers:
USA: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036.
EUROPE: Motorola Ltd.; European Literature Centre; 88 Tanners Drive, Blakelands, Milton Keynes, MK14 5BP, England.
JAPAN: Nippon Motorola Ltd.; 4-32-1, Nishi-Gotanda, Shinagawa-ku, Tokyo 141 Japan.
ASIA-PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Center, No. 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong.